





Phase Control Thyristor

DS5811-3 January 2014 (LN31255)

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V _{DRM} and V _{RRM} V	Conditions
DCR2150C42 DCR2150C40 DCR2150C35 DCR2150C30	4200 4000 3500 3000	$\begin{array}{l} T_{vj}=-40^{\circ}C \ to \ 125^{\circ}C, \\ I_{DRM}=I_{RRM}=200 mA, \\ V_{DRM}, \ V_{RRM} \ t_{p}=10 ms, \\ V_{DSM} \ \& \ V_{RSM}= \\ V_{DRM} \ \& \ V_{RRM} \ + 100 V \\ respectively \end{array}$

Lower voltage grades available.

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

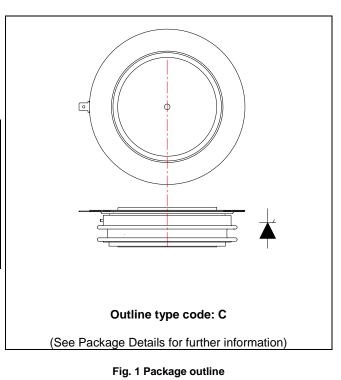
DCR2150C42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

4200V
2150A
29000A
1500V/µs
400A/µs

* Higher dV/dt selections available





CURRENT RATINGS

 $T_{case} = 60^{\circ}C$ unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Sid	de Cooled			
I _{T(AV)}	Mean on-state current	Half wave resistive load	2150	А
I _{T(RMS)}	RMS value	-	3377	А
Ι _Τ	Continuous (direct) on-state current	-	3280	А

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I _{TSM}	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 125^{\circ}C$	29.0	kA
l ² t	I ² t for fusing	$V_R = 0$	4.2	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
R _{th(j-c)}	Thermal resistance – junction to case	Double side cooled	DC	-	0.0101	°C/W
		Single side cooled	Anode DC	-	0.0176	°C/W
			Cathode DC	-	0.0239	°C/W
R _{th(c-h)}	Thermal resistance – case to heatsink	Clamping force 37kN	Double side	-	0.0025	°C/W
		(with mounting compound)	Single side	-	0.005	°C/W
T_{vj}	Virtual junction temperature	Blocking V _{DRM} / _{VRRM}		-	125	°C
T _{stg}	Storage temperature range			-55	125	°C
Fm	Clamping force			33.0	41.0	kN



DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I _{RRM} /I _{DRM}	Peak reverse and off-state current	At V _{RRM} /V _{DRM} , T _{case} = 125°C		-	200	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V _{DRM} , T _j = 125°C, ga	ate open	-	1500	V/µs
dl/dt	Rate of rise of on-state current	From 67% V_{DRM} to 2x $I_{T(AV)}$	Repetitive 50Hz	-	200	A/µs
		Gate source 30V, 10Ω ,	Non-repetitive	-	400	A/µs
		$t_r < 0.5 \mu s, T_j = 125^{\circ}C$				
V _{T(TO)}	Threshold voltage – Low level	500A to 2000A at $T_{case} = 125$	5°C	-	0.9	V
	Threshold voltage – High level	2000A to 7000A at $T_{case} = 12$	25°C	-	1.08	V
۲ _T	On-state slope resistance – Low level	500A to 2000A at T _{case} = 125	5°C	-	0.36	mΩ
	On-state slope resistance – High level	2000A to 7000A at $T_{case} = 12$	25°C	-	0.265	mΩ
t _{gd}	Delay time	$V_D = 67\% V_{DRM}$, gate source	30V, 10Ω	-	3	μs
		$t_r = 0.5 \mu s, T_j = 25^{\circ}C$				
tq	Turn-off time	$T_j = 125^{\circ}C, V_R = 200V, dI/dt$	= 1A/µs,	250	500	μs
		$dV_{DR}/dt = 20V/\mu s$ linear				
Q_S	Stored charge	$I_T = 2000A, T_j = 125^{\circ}C, dI/dt$	– 1A/µs,	1000	3000	μC
١L	Latching current	$T_j = 25^{\circ}C, V_D = 5V$		-	3	А
Ι _Η	Holding current	$T_j = 25^{\circ}C, R_{G-K} = \infty, I_{TM} = 50$	0A, I _T = 5A	-	300	mA



GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V _{GT}	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	1.5	V
V_{GD}	Gate non-trigger voltage	At 50% V _{DRM} , T _{case} = 125°C	0.4	V
I _{GT}	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	350	mA
I _{GD}	Gate non-trigger current	At 50% V _{DRM} , T _{case} = 125°C	10	mA

CURVES

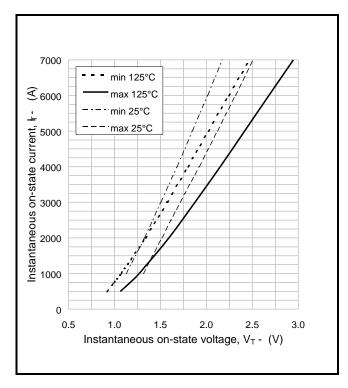


Fig.2 Maximum & minimum on-state characteristics

V_{TM} EQUATION

Where A = 0.137154B = 0.132631 $V_{TM} = A + BIn (I_T) + C.I_T + D.\sqrt{I_T}$ C = 0.000248D = -0.001126 these values are valid for T_j = 125°C for I_T 100A to 7000A



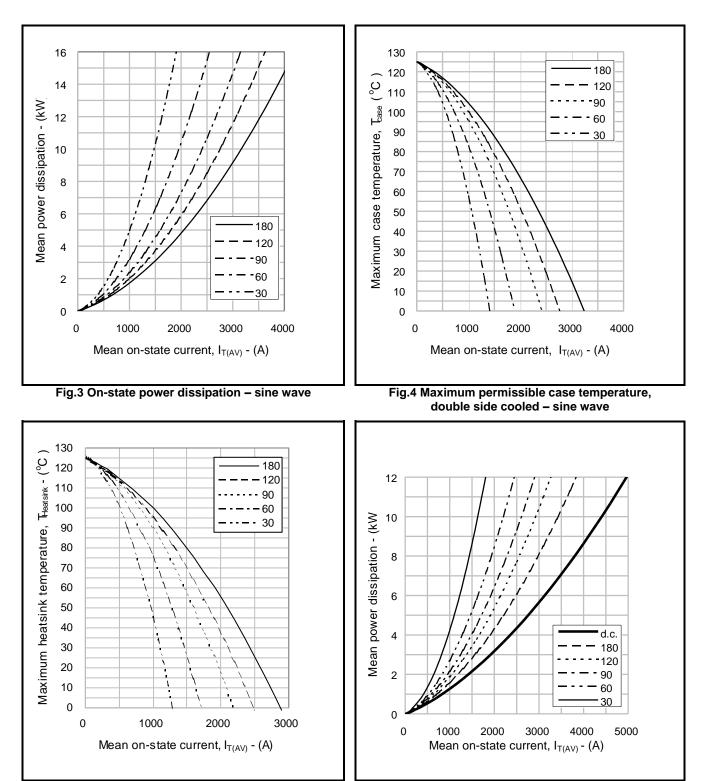
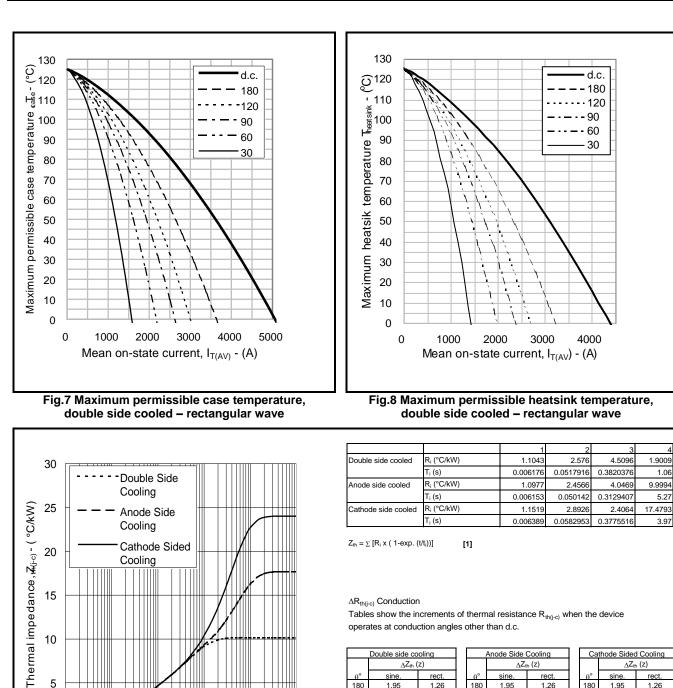


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

Fig.6 On-state power dissipation - rectangular wave

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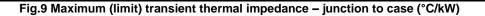


 $Z_{th} = \sum [R_i x (1-exp. (t/t_i))]$ [1]

 $\Delta R_{\text{th(j-c)}} \text{ Conduction}$

Tables show the increments of thermal resistance $\mathsf{R}_{\mathsf{th}(j\text{-}c)}$ when the device operates at conduction angles other than d.c.

	Double side cooling			Anode Side Cooling			Cathode Sided Cooling		
	ΔZ_{th}	(z)		ΔZ	_{th} (z)		ΔZ_t	_h (z)	
θ°	sine.	rect.	θ°	sine.	rect.	θ°	sine.	rect.	
180	1.95	1.26	180	1.95	1.26	180	1.95	1.26	
120	2.32	1.89	120	2.32	1.89	120	2.31	1.88	
90	2.74	2.27	90	2.74	2.27	90	2.72	2.26	
60	3.14	2.70	60	3.14	2.70	60	3.12	2.68	
30	3.46	3.19	30	3.46	3.19	30	3.43	3.17	
15	3.61	3.47	15	3.62	3.47	15	3.58	3.44	
	θ° 180 120 90 60 30	ΔZ _{th} θ° sine. 180 1.95 120 2.32 90 2.74 60 3.14 30 3.46	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	



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20

15

10

5

0

0.001

111

0.01

0.1

1

Time - (s)

10

Cooling

BYNEX SEMICONDUCTOR



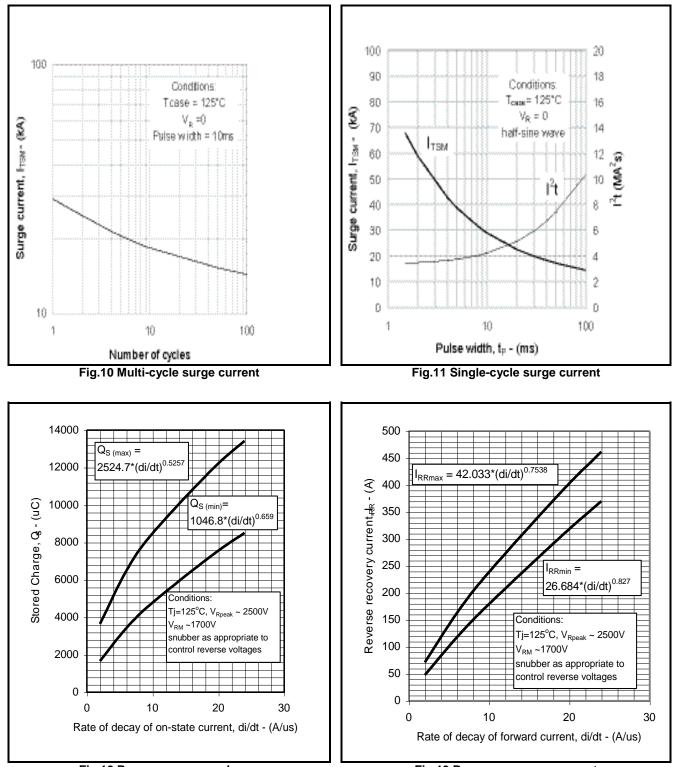
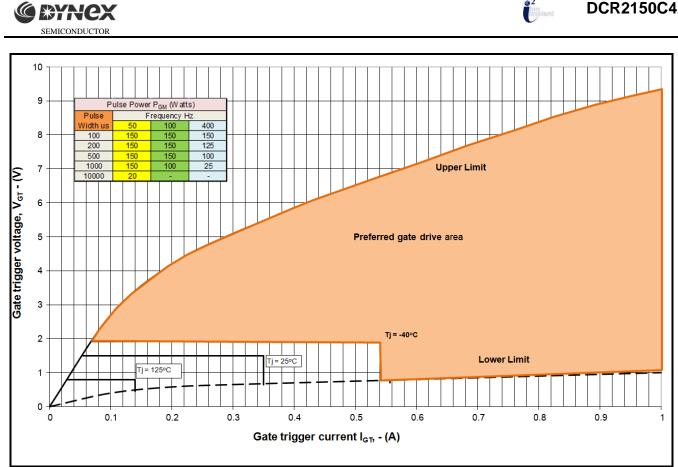


Fig.12 Reverse recovery charge

Fig.13 Reverse recovery current

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Fig14 Gate Characteristics

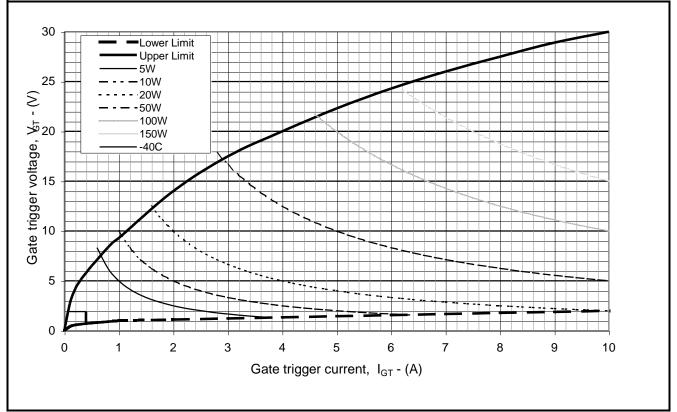


Fig. 15 Gate characteristics



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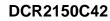
PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

SIDANGLE PROJECTION ONOT SCALE FIN DOUBTASK Image: constrained by the state of	Device DCR2860C22 DCR2630C28 DCR1950C52 DCR1650C65 DCR1370C85	Maximum Thickness (mm) 26.415 26.49 26.76 26.84 27.1 27.46	
Lead length: 420n Lead terminal connector Package outline type o	: M4 ring		

Fig.16 Package outline





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